Introduction to COST 531-A European Action on Lead-free Soldering

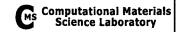
Hyuck-Mo Lee (KAIST/Korea)

Introduction to COST 531

Hyuck Mo Lee

Department of Materials Science and Engineering KAIST

KAIST

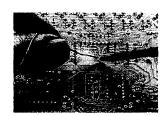


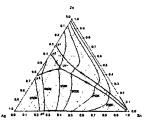
COST 531

A European Action on Lead-free Soldering

Herbert Ipser

Chairman of the Management Committee Institut für Anorganische Chemie, Universität Wien A-1090 Wien, Austria







http://www.ap.univie.ac.at/users/www.cost531/





COST

COopération européenne dans le domaine de la recherche Scientifique et Technique

European **CO**operation in the Field of **S**cientific and **T**echnical Research



Institut für Anorganische Chemie der Universität Wien



What is COST?

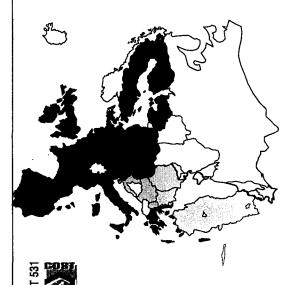
http://www.cordis.lu/cost/

- Intergovernmental co-operation (basic, pre-competitive research)
 - founded 1971
 - . 19 Scientific & Technical domains (one of them: Materials)
- Participation
 - 34 COST Member States + 1 Co-operating Country (Israel)
 - International organizations and research establishments from non-COST countries
 - . The European Commission
- COST Actions
 - . Concerted Actions (Networks) of nationally funded R&D
 - . Memorandum of Understanding (MoU)





COST Countries



COST Member States

- The 25 EU Member States¹
- EFTA Member States
- ➤ Iceland
- ➤ Norway
- > Switzerland
- Candidate Countries
- > Bulgaria
- ➤ Romania
- ➤ Turkey
- Other Countries
- ➤ Serbia and Montenegro²
- ➤ Croatia²
- ➤ FYR of Macedonia (FYROM)²

COST Co-operating States

➤ israe

¹ from 1 May 2004

² not associated to FP



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COST Characteristics

- Individual projects of a COST Action must be financed nationally
- COST provides financial support for networking
 - a) Meetings, conferences, workshops
 - b) Exchange of (young) scientists (STSMs = Short Term Scientific Missions)
- Individual projects grouped into Group Projects (at least three projects from at least two different countries)
- **■** Group projects may be collected in Working Groups
- **COST Action is coordinated by a Management Committee (MC)**
- All Actions within a Scientific Domain are coordinated by a Technical Committee (TC)
- Above all Committee of Senior Officials (CSO) as political level





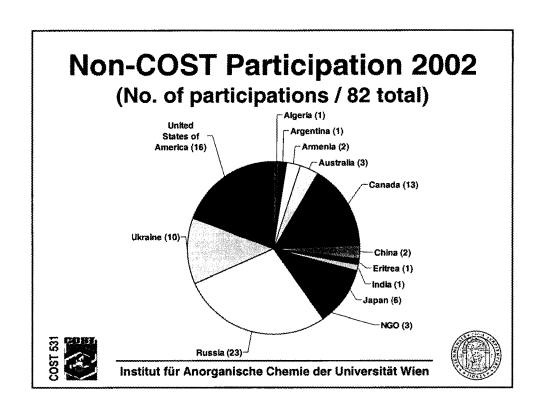
Organizations from non-COST countries

May participate on an Action by Action basis, given:

- · there is mutual S&T benefit
- the CSO approves (following MC and TC approval)
- participation is confirmed by an exchange of letters between the organization and the CSO
- Non-COST institutions may not vote in the MC







COST Action 531 Lead-free Solder Materials Background

No lead anymore in electrical and electronic equipment in Europe from July 1st, 2006, on!

- **■** Directive on Waste Electrical and Electronic Equipment (WEEE)
- Directive on the Restriction of the Use of Certain Hazardous Substances in Electrical and Electronic Equipment (RHS)

published in the Official Journal of the European Union 13.02.2003



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COST Action 531 Lead-free Solder Materials Aim

- A better lead-free solder Better than what?

On what criteria?

Processability, Performance, Price





COST Action 531 Lead-free Solder Materials Systems of Interest

- tin-silver (Sn-Ag) based systems
- **n** tin-copper (Sn-Cu) based systems
- n tin-indium (Sn-In) based systems
- n tin bismuth (Sn-Bi) based systems
- n tin-zinc (Sn-Zn) based systems
- alternate solder systems



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COST Action 531 Lead-free Solder Materials 20 Signatory Countries in Europe

Austria Greece Slovenia Hungary Ireland Spain Bulgaria applied Croatia Italy Sweden **Netherlands** Switzerland **Belgium** Czech Republic Finland Poland **United Kingdom** ??? France Portugal Yugoslavia Slovakia Germany



approx. 40 research institutions from 15 European countries



iversität Wien

COST Action 53¹ Lead-free Solder Materials

2 non-COST Institutions:

- MMO (Materials and Manufacturing Ontario, Canada)
- CMAP (Centre for Microelectronics Assembly and Packaging, Canada)

letter of application to join from:

• National Cheng Kung University (Tainan, Taiwan)

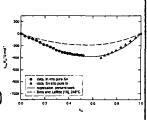


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COST Action 531 Lead-free Solder Materials 4 Working Groups

WG 1: Experimental thermodynamic properties of alloy systems and experimental phase diagrams (Coordinator: Bernard Legendre, Paris, France)



WG 2: Theoretical modeling of phase diagrams (Coordinator: Leszek Zabáyr, Kraków, Poland)



COST Action 531 Lead-free Solder Materials

4 Working Groups

a = 90°

WG 3-4: Physical and chemical properties of alloy systems as well as of solder joints

(wettability, surface tension, viscosity, ...; ductility, strength, fatigue, ...; toxicity, ...)

(Coordinator: William J. Plumbridge, Milton Keyne, United Kingdom)

WG 5-6: Reliability issues, packaging and miniaturization

(thermal fatigue, mechanical fatigue, ...) (Coordinators: *Bernd Michel*, Berlin, Germany, and *John Botsis*, Lausanne, Switzerland) Assemblies

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10 Group Projects

No.			
GP1	PL 1-1 Leszek A. Zabdyr (5 partners: A, POL, UK)	Krakow (POL)	Physico-chemical properties of some Ag-based ternary alloys as possible materials for lead-free solders
GP2	IT 2-1 Riccardo Ferro (6 partners: I, F, UK)	Genoa (I)	Contribution to the constitutional characterisation of lead- free alloys as soldering materials
GP3	FR 3-1 Fiqiri Hodaj (5 partners: A, F, NL, FIN)	Grenoble (F)	Interfacial reactions in SnAgCu based solder Interconnects and multilayer assemblies
GP4	AT 4-1 Herbert Ipser (7 partners: A, I, CZ, POL)	Vienna (A)	Silver-Indium-Tin Alloys as Possible Lead-free Soldering Materials: Interaction with Ni and Pd as Substrates
GP5	PT 5-1 Delfim Soares (7 partners: PT, POL, BG, F)	Minho (PT)	Physical and technological properties of Sn-Zn- and Sn-Bi-X based lead-free alloys
GP6	DE 6-1 Günter Effenberg (3 partners: D, UK, NL)	Stuttgart (D)	Lead-free tin based solders and coatings, wetting behaviour, interdiffusion, phase equilibria
GP7	PL 7-1 Natalia Sobczak (7 partners: POL, CH, SK, A, BG, UK)	Krakow (POL)	Prediction of the next generation of lead-free solders
GP8	PL 8-1 Krzysztof Fitzner (6 partners: POL, YU, F, CZ, SLO)	Krakow (POL)	Thermodynamic Properties and Phase Equilibria of Silver Ternary Alloys with Indium, Antimony and Tin
GP9	DE 9-1 Georg Schmitz (6 partners: D, UK, POL, CH)	Aachen (D)	Control of Microstructure Evolution and its impact on Solder Joint Performance
GP10	CH10-1 John Botsis *	Lausanne (CH)	Identification of mechanical behavior of lead-free materials subjected to structural constraints

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* proposed



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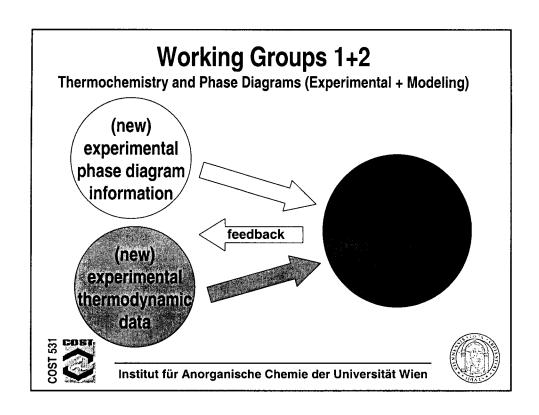
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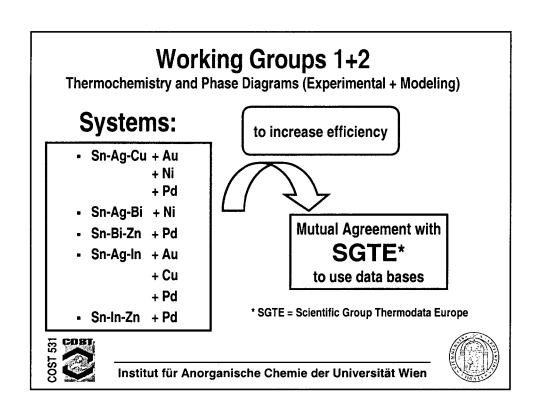
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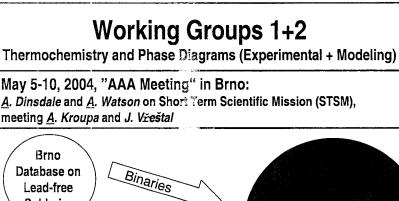
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SGTE Database on Lead-free Soldering

Brno Database on

> Lead-free Soldering



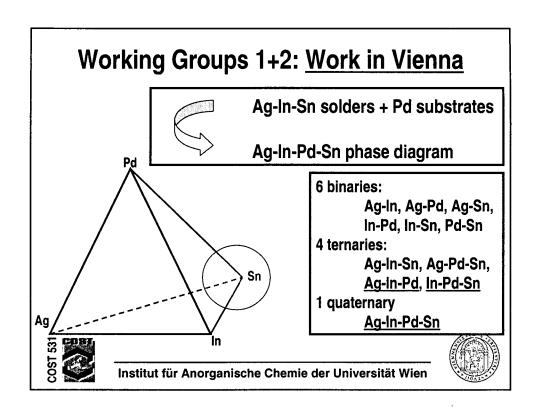
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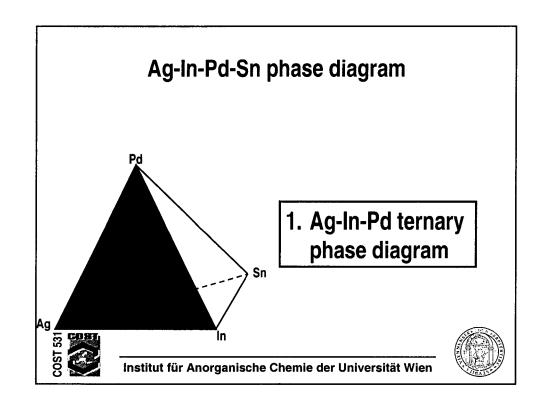
Working Groups 1+2: Work in Vienna

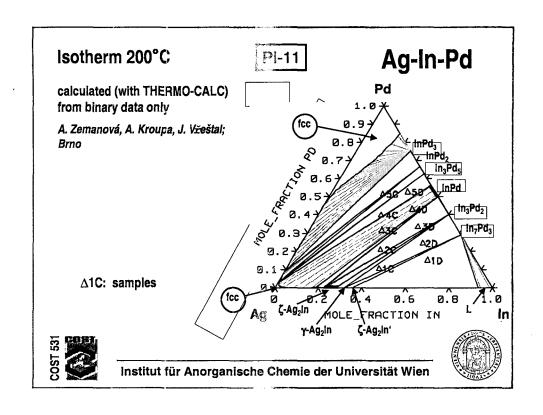
Group Project GP4:

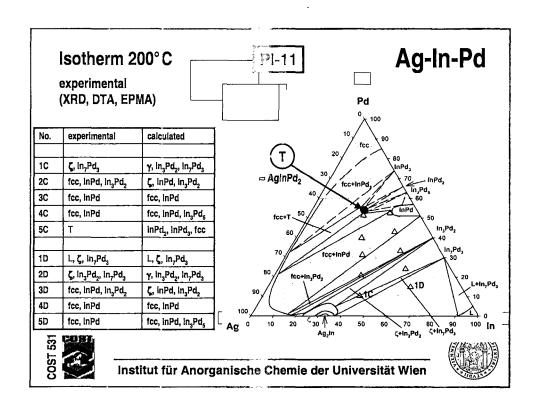
"Ag-In-Sn Alloys as Possible Lead-free Soldering Materials: Interaction with Ni and Pd as Substrates"

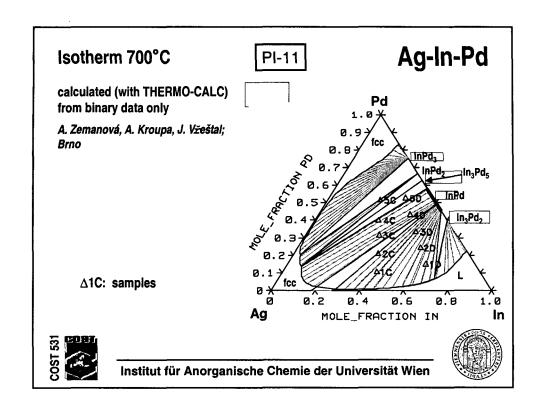
	Partners	City / Country	Main Contribution
	H. Ipser (Coordinator)	Vienna / A	Phase diagram investigations and experimental thermodynamics (calorimetry)
AT 4-2	R. Stickler	Vienna / A	(Retired)
AT 4-3	B. Weiss	Vienna / A	Mechanical properties of solder joints
IT 4-4	G. Borzone	Genoa / I	Calorimetric measurements
PL 4-5	L. Zabdyr	Cracow / PL	emf-measurements
CZ 4-6	J. Vrestal	Brno / CZ	Phase diagram calculations
CZ 4-7	A. Kroupa	Brno / CZ	Phase diagram calculations

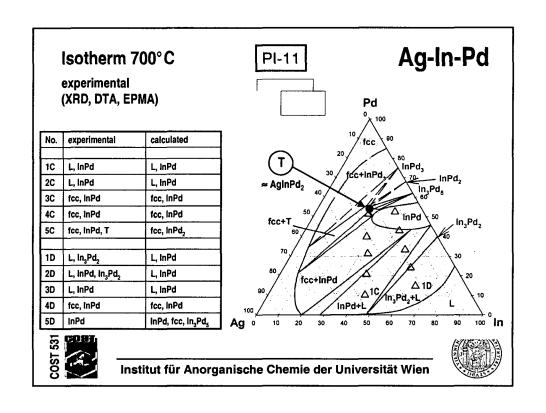


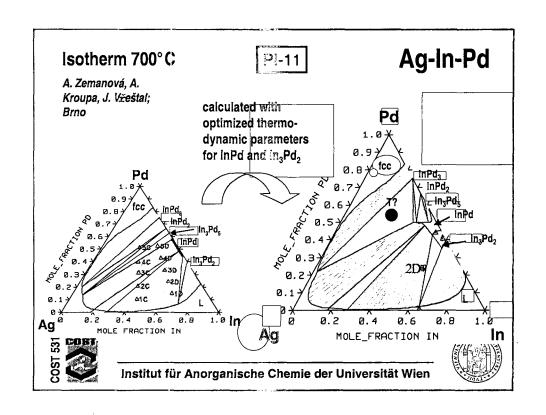


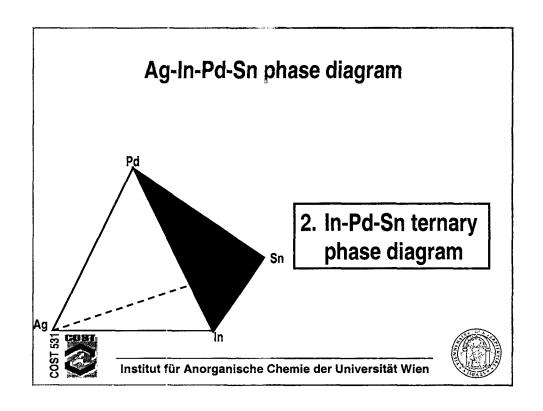








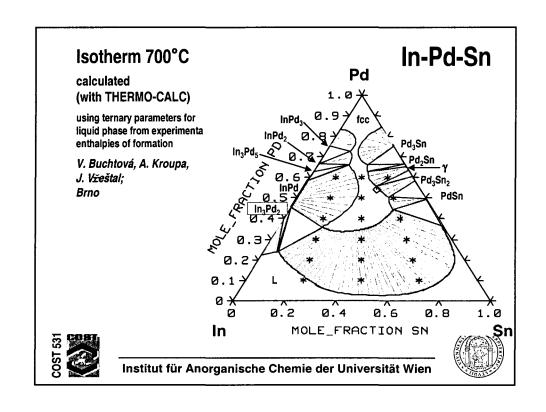


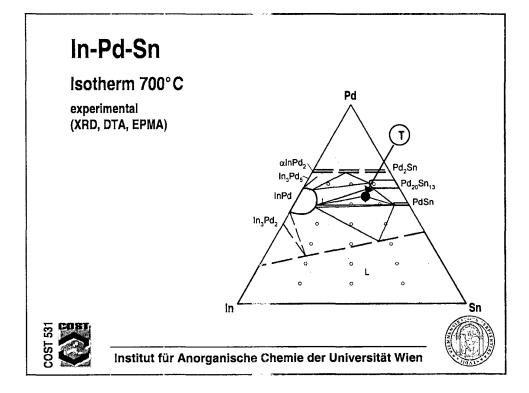


Enthalpies of Mixing of liquid alloys (in kJ mol⁻¹) by drop calorimetry at 900°C

exp. values fitted by a Redlich-Kister-Muggianu polynomial

liquid at 900°C





ELFNET

(European Lead-Free Soldering NETwork) a Coordination Action within FP6

- Coordinated by ITRI Ltd. (International Tin Research Institute)
- 36 participants from 19 European countries
- **Budget of 2.3 million EURO**
- Contract signed in April 2004
- Overlap with COST 531 (alphabetical):

EMPA (Swiss Fed. Lab. for Materials Testing and Research) Helsinki University of Technology Institute of Metallurgy and Materials Science, Polish Academy of Sciences Institute of Physics of Materials, Czech Academy of Sciences (NMRC - University College Cork)

(Siemens Germany)

TU Berlin / Fraunhofer Institute for Reliability and Microintegration IZM University of Vienna



COST 531: Wrap-up

 March 3/4, 2005:
 COST 531 Midterm-Conference in Lausanne, Switzerland organized by Prof. John Botsis (EPFL)



- Information on COST 531 http://www.ap.univie.ac.at/users/www.cost531/
- Information on COST http://cost.cordis.lu/cost

COST 531

